



Trench Field Stop Fast IGBT Co-packed with Thin SiC Schottky Diode

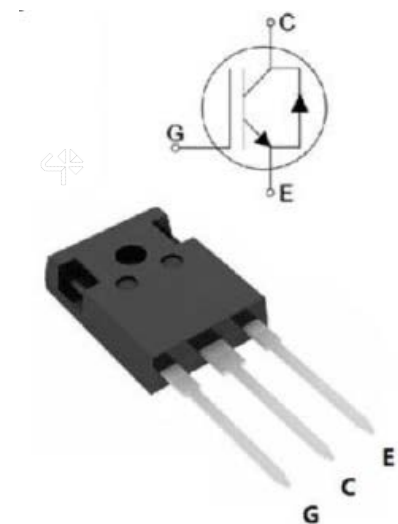
Type	V_{CE}	I_C	$V_{CEsat}, T_{vj}=25^{\circ}C$	T_{vjmax}	Package
SKIS75N120-T7	1200V	75A	2V	150°C	TO247

Features and Benefits

- Low switching losses due to the combination of trench field stop fast IGBT and thin SiC Schottky Diode
- Better efficiency and cost balance than SiC MOSFET solution
- High ruggedness

Applications

- Charger
- Solar inverter
- Energy storage
- Industrial UPS



	Parameter		Unit
V_{CE}	Max Collector-Emitter Voltage	1200	V
$I_{C(Nominal)}$	Max DC Collector Current	75	A
V_f	SiC Schottky Diode Typical Forward Voltage at 40A	1.75	V
Q_c	SiC Schottky Diode Total Capacitive Charge	123	nC



Maximum Ratings

	Parameter	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	1200	—	—	V
I_C	DC collector current limited by T_{jmax}				
	$T_c = 25^{\circ}C$	—	—	100	A
	$T_c = 100^{\circ}C$	—	—	75	A
I_F	Diode Forward current, limited by T_{jmax}				
	$T_c = 25^{\circ}C$	—	—	75	A
	$T_c = 100^{\circ}C$	—	—	35	A
V_{GE}	Continuous Gate-emitter voltage	-20	—	20	V
V_{GE}	Transient Gate-emitter voltage	-30	—	30	V
I_{Fpulse}	Diode Pulsed Current, t_p limited by T_{jmax} $t_p = 10$ ms, Half Sine Wave	—	—	170	A
P_{tot}	Power dissipation , $T_j=25^{\circ}C$	—	—	312	W
T_{vj}	Operating junction temperature	-40	—	150	$^{\circ}C$
T_{stg}	Storage temperature -	-55	—	150	$^{\circ}C$

Thermal Resistance

Parameter	Symbol	Max. Value	Unit
IGBT thermal resistance junction - case	$R_{\theta(j-c)}$	0.4	K/W
Diode thermal resistance, junction - case	$R_{\theta(j-c)}$	0.7	K/W
Thermal resistance, junction - ambient	$R_{\theta(j-a)}$	38	K/W

Static Characteristics. $T_j=25^{\circ}C$

	Parameter	Min.	Typ.	Max.	Unit	Conditions
$V_{CE(sat)}$	Collector-to-Emitter Saturated Voltage	—	2	—	V	$V_{GE} = 15V, I_C = 75A$
		—	2.5	—		$T_j=25^{\circ}C$
		—	—	—		$T_j=150^{\circ}C$
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	4.8	5.5	6.2	V	$I_C = 250\mu A, V_{GE} = V_{CE}$
I_{CES}	Zero Gate Voltage Collector Current	—	—	1	mA	$V_{CE} = 1200V, V_{GE} = 0V,$
		—	—	5		$T_j=25^{\circ}C$
		—	—	—		$T_j=150^{\circ}C$
I_{GES}	Gate Emitter Leakage Current	—	—	200	nA	$V_{CE} = 0V, V_{GE} = 20V$
C_{ies}	Input Capacitance	—	4600	—	pF	$V_{GE} = 0V, V_{CE}=25V, f=1MHz$
C_{oes}	Output Capacitance	—	210	—		
C_{res}	Reverse Transfer Capacitance	—	25	—		
Q_g	Gate charge	—	128	—	nC	$V_{CC}=960V, I_C=75A, V_{GE}=15V$



Switching Characteristic, Inductive Load

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Turn-on delay time	$t_{d(on)}$	—	79	—	ns	$V_{CC} = 600V$, $I_C = 75A$, $V_{GE} = 0/15V$, $R_g = 20\Omega$ $T_{VJ} = 25^\circ C$
Rise time	t_r	—	131	—	ns	
Turn-off delay time	$t_{d(off)}$	—	211	—	ns	
Fall time	t_f	—	81	—	ns	
Turn-on energy E_{on}	E_{on}	—	5.25	—	mJ	
Turn-off energy	E_{off}	—	3.68	—	mJ	
Total switching energy	E_{ts}	—	8.93	—	mJ	

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Turn-on delay time	$t_{d(on)}$	—	72	—	ns	$V_{CC} = 600V$, $I_C = 75A$, $V_{GE} = 0/15V$, $R_g = 20\Omega$ $T_{VJ} = 150^\circ C$
Rise time	t_r	—	134	—	ns	
Turn-off delay time	$t_{d(off)}$	—	240	—	ns	
Fall time	t_f	—	110	—	ns	
Turn-on energy E_{on}	E_{on}	—	5.65	—	mJ	
Turn-off energy	E_{off}	—	4.56	—	mJ	
Total switching energy	E_{ts}	—	10.2	—	mJ	

Diode Characteristic

	Parameter	Min.	Typ.	Max.	Unit	Conditions
V_f	Forward Voltage	—	1.75	—	V	$I_f = 40A$, $T_J = 25^\circ C$
		—	2.53	—		$I_f = 40A$, $T_J = 150^\circ C$
Q_c	Total Capacitive Charge	—	123	—	nC	$V_R = 800V$
C	Total Capacitance	—	1794	—	pF	$V_R = 0V$, $T_J = 25^\circ C$, $f = 1MHz$
		—	120	—		$V_R = 400V$, $T_J = 25^\circ C$, $f = 1MHz$
		—	75	—		$V_R = 800V$, $T_J = 25^\circ C$, $f = 1MHz$

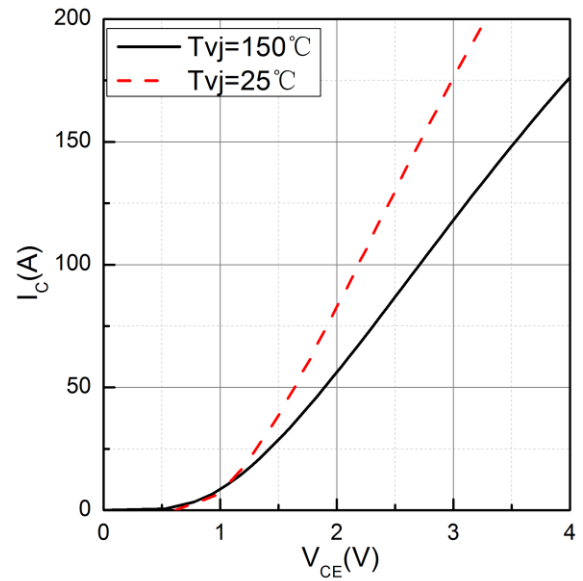
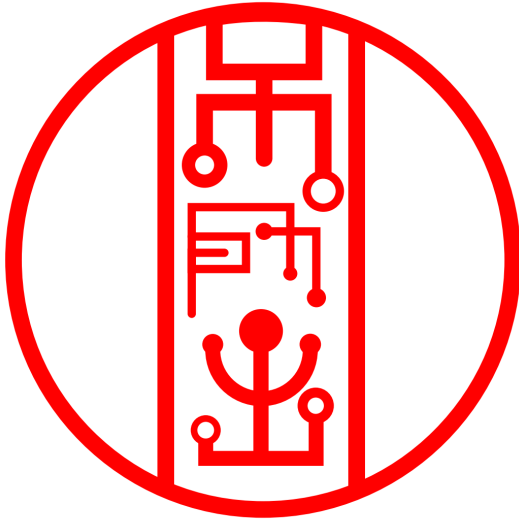


Figure 2. Typical output characteristic($V_{GE}=15V$)

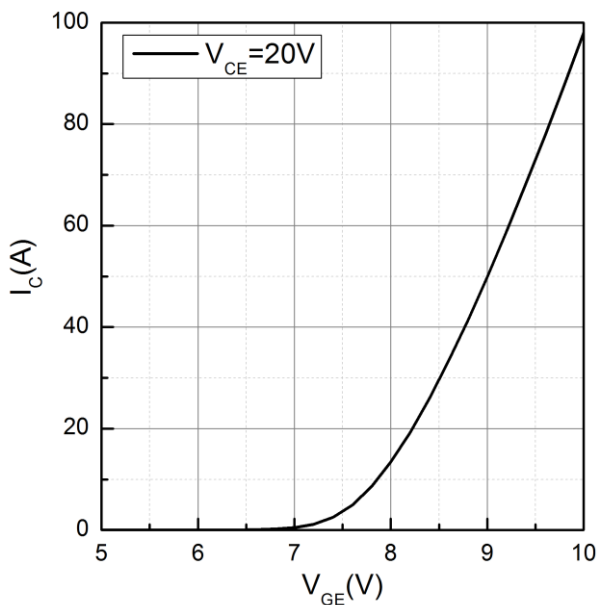


Figure3. Transfer characteristic($T_{vj}=25^{\circ}C$)

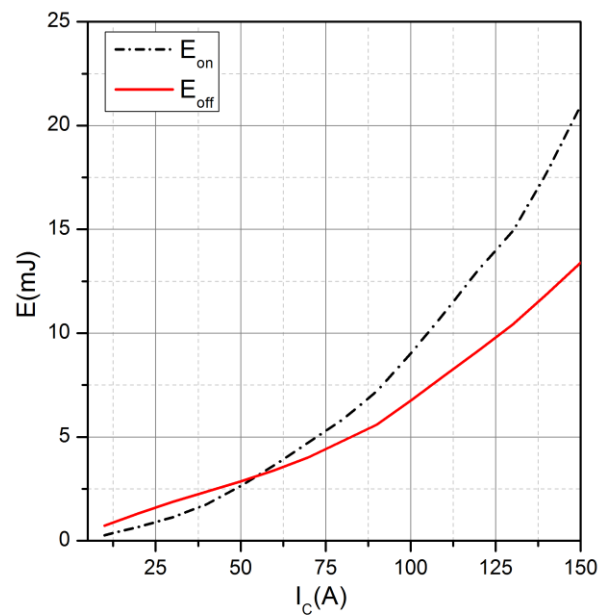


Figure 4. Typical energy losses as function of collector current(inductive load, $T_{vj}=150^{\circ}C$, $V_{CE}=600V$, $V_{GE}=15/0V$, $R_G=10\Omega$, Dynamic test circuit in figure E)

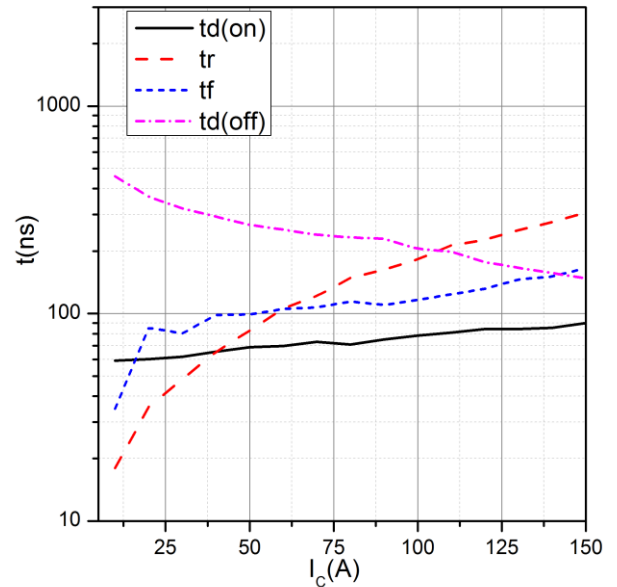
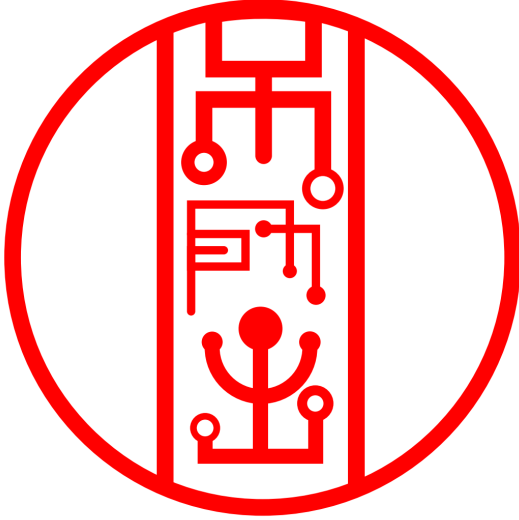


Figure 6. Typical switching times as function of collector current(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $R_G=10\Omega$, Dynamic test circuit in figure E)

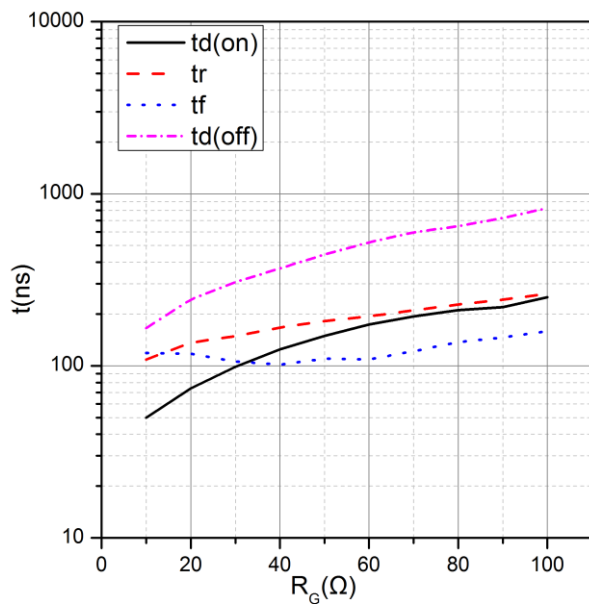


Figure 7. Typical switching times as function of gate resistor(inductive load, $T_{vj}=150^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=40\text{A}$, Dynamic test circuit in figure E)

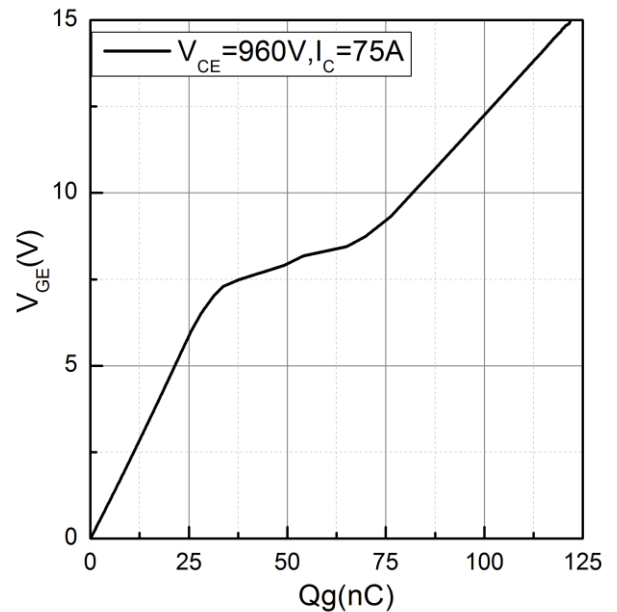


Figure 8. Gate charge characteristic

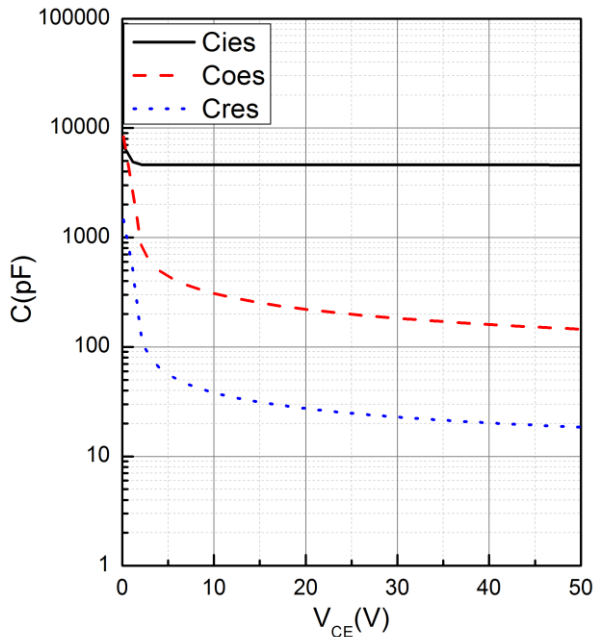
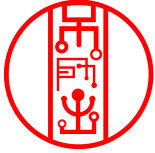


Figure 9. Typical capacitance as a function of collector-emitter voltage ($V_{GE}=0V$, $f=1MHz$)

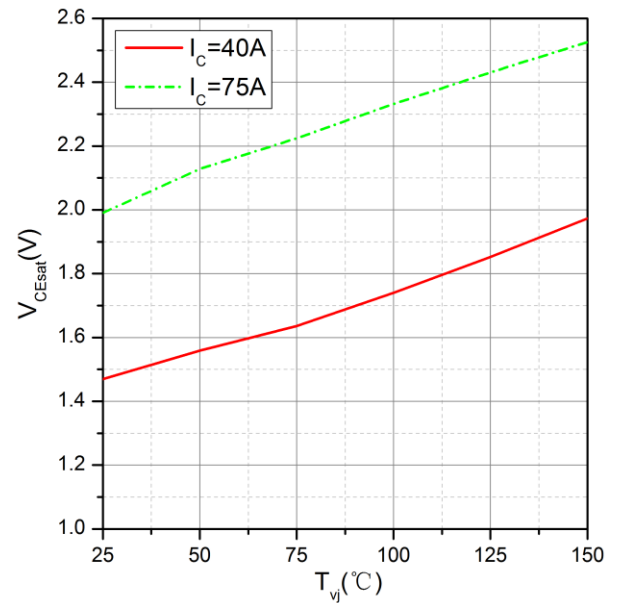


Figure 10. Typical collector-emitter saturation voltage as a function of junction temperature ($V_{GE}=15V$)

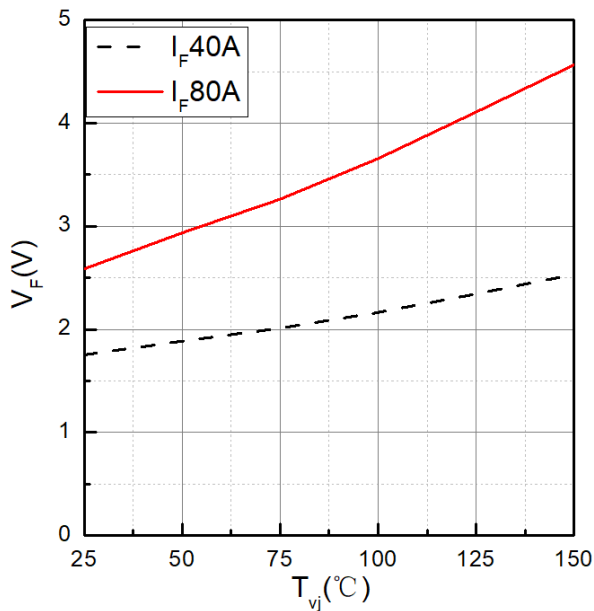


Figure 12. Typical diode forward voltage as a function of junction temperature

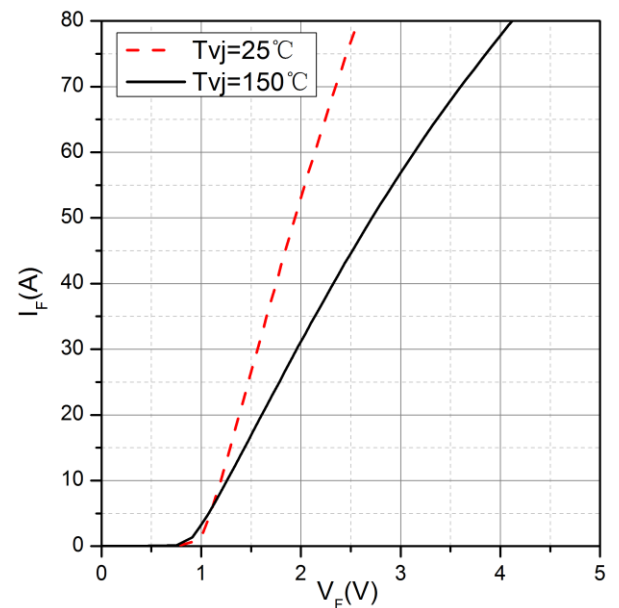


Figure 12. Typical diode forward current as a function of forward voltage

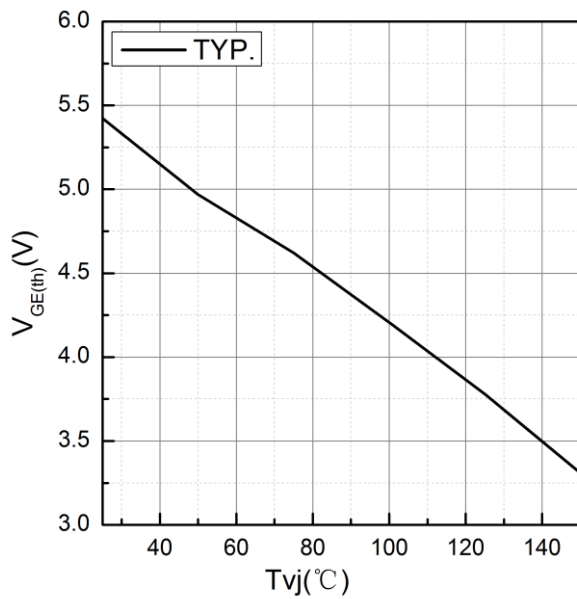
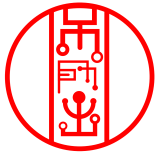


Figure 13. Gate-emitter threshold voltage as a function of junction temperature ($I_c = 0.25mA$)

